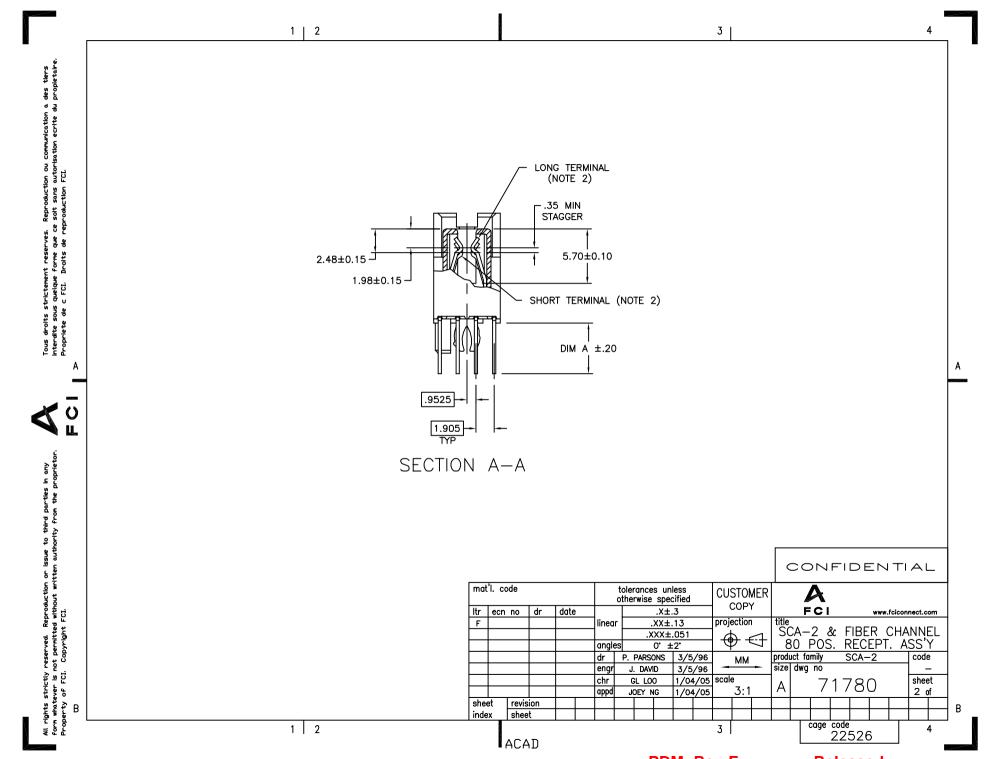


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NOTES: ① TRUE POSITION NOTES APPLY AT TERMINAL TIP. ② CONTACTS IN POSITIONS 2 THRU 35, 44 AND 47 THRU 74 ARE SHORT TERMINALS. CONTACTS IN POSITIONS 1, 36 THRU 43, 45, 46, AND 75 THRU 80 ARE LONG TERMINALS. CONTACTS IN POSITIONS 1, 36 THRU 43, 45, 46, AND 75 THRU 80 ARE LONG TERMINALS. CONTACTS IN POSITIONS 1, 36 THRU 43, 45, 46, AND 75 THRU 80 ARE LONG TERMINALS. CONTACTS IN POSITIONS 1, 36 THRU 43, 45, 46, AND 75 THRU 80 ARE LONG TERMINALS. COMPONENT SIDE RECOMMENDED PC BOARD MOUNTING DIMENSIONS CON					1 2						3			4	
-002 2.79 NO		PRODUCT NO.	"A" DIM		PLATING	RECOMMEDED P.C. E	BOARD THICKNESS	PROI	PRODUCT NO. PLATING						
-002 2.79 NO		71780-001 2.79 YES				1.57mm (0.06	1.57mm (0.062")								
DIESTIN NOTES DIESTIN NOTES APPLY AT TERMINAL TIP. 2.60±0.10 DIA NOTES DIESTIN NOTES APPLY AT TERMINAL TIP. 2.60±0.10 DIA NOTES DIESTIN NOTES APPLY AT TERMINAL TIP. 2.60±0.10 DIA NOTES DIESTIN NOTES APPLY AT TERMINAL TIP. 2.60±0.10 DIA NOTES DIESTIN NOTES APPLY AT TERMINAL TIP. 2.60±0.10 DIA NOTES DIESTIN NOTES APPLY AT TERMINAL TIP. 2.60±0.10 DIA NOTES DIESTIN NOTES APPLY AT TERMINAL TIP. 2.60±0.10 DIA NOTES DIESTIN NOTES APPLY AT TERMINAL S. CONTACTS IN POSITION S 2 THRU 35, 44 AND AT 75 THRU 90 APE LONG TERMINALS. DIESTIN NOTES APPLY AT TERMINALS. DIESTIN NOTES		T					JZ)	-102		<u> </u>					
-0.04 3.18 NO		-003	3.18	YES	NOTE (4)	2.36mm (0.09	9 <i>3"</i>)		-103	NOTE 6					
T1780-006 4.06 NO		-004	3.18	NO	11012 ()	2.00///// (0.00			-104						
NOTE 5		-005	25 ")		-105										
POSN 40 POSN 80 POSN 41 POSN 80 POSN 41 POSN 40 POSN 80 POSN 41 POSN 41 POSN 40 POSN 40 POSN 41 POSN 1 RECOMMENDED PC BOARD MOUNTING DIMENSIONS COMPONENT SIDE POSN 41 POSN 1 RECOMMENDED PC BOARD MOUNTING DIMENSIONS COMPONENT SIDE CONTACT PLATING: 30µ" (0,76 µm) MIN. GOLD PLATING OVER 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA. 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. POSN 41 POSN 41 POSN 41 POSN 41 POSN 41 POSN 1 RECOMMENDED PC BOARD MOUNTING DIMENSIONS COMPONENT SIDE CONTACT PLATING: 30µ" (0,76 µm) MIN. GOLD PLATING OVER 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN. NICKLE UNDERPLATE IN P.C. BOARD IES AREA 50µ" (1,27 µm) MIN		71780-006	4.06	NO		(01.2		717	80-106						
POSN 40 POSN 80 POSN 80 POSN 80 POSN 41 PO									—— NOTE	6 —					
OVER 50u" (1.27um) NICKLE MIN. UNDERPLATE IN CONTACT AREA. 100u" (2.54um) MIN. TIN-LEAD PLATING OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE IN P.C. BOARD LEG AREA. 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. (5) DIMENSIONS DO NOT APPLY TO CONNECTOR STYLES WITHOUT POLARIZATION PEG. (SEE CHART) (6) CONTACT PLATING: 30u" (0.76um) MIN. GOLD PLATING OVER 50u" (1.27um) NICKLE MIN. UNDERPLATE IN CONTACT AREA. 100u" (2.54um) MIN. TIN-LEAD PLATING OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE IN P.C. BOARD LEG AREA. 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE IN P.C. BOARD LEG AREA. 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. OVER 50u" (1.27um) MIN. OVER 50u (1.27um) MIN. OVER 50u (1.27um) MIN. OVER 50u (1.27um) MIN. OVE		POSN 40 POSN 80 POSN 41 POSN 1 RECOMMENDED PC BOARD MOUNTING DIMENSIONS COMPONENT SIDE MOUNTING DIMENSIONS COMPONENT SIDE													
		OVER 100u" NICKLE NICKLE DIMEN: POLAR OVER 100u" NICKLE	50u" (1.27 (2.54um) E UNDERPL E UNDERPL SIONS DO IZATION PE CT PLATINO 50u" (1.27 (2.54um) E UNDERPL	'um) NICKLE MIN MIN. TIN-LEAD ATE IN P.C. BOA ATE OVER REMAI NOT APPLY TO (G. (SEE CHART) S: 30u" (0.76um 'um) NICKLE MIN MIN. TIN-LEAD ATE IN P.C. BOA	I. UNDERPLATE PLATING OVER RD LEG AREA. NING AREA. CONNECTOR ST MIN. GOLD F I. UNDERPLATE PLATING OVER RD LEG AREA.	IN CONTACT AREA. 50u" (1.27um) MIN. 50u" (1.27um) MIN. YLES WITHOUT PLATING IN CONTACT AREA. 50u" (1.27um) MIN.	Itr ecn no dr	date	other linear angles dr P. F engr J. chr G	wise specified	COPY projection MM scale	FCI title SCA-2 & 80 POS. product family size dwg no	www.fo FIBER C RECEPT. SCA-2	HANNEL ASS'Y	- - -
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PRODUCT NO.		"A" DIM POLARIZATION PEG		PLATING	RECOMMEDED P.C. BOARD THICKNESS	PRO	DDUCT NO.	PLATING
71780-001LF		2.79	9 YES		1.57mm (0.062")	717	780-101LF	
	-002LF	2.79 NO			1.5711111 (0.002)		-102LF	
	-003LF	-003LF 3.18 YES	NOTE (8)	2.36mm (0.093")		-103LF	NOTE (7)	
	-004LF	3.18	NO	NOIL®	2.5611111 (0.093)		-104LF	NOIL
	-005LF	4.06	YES		3.18mm (0.125")		-105LF	
71780-006LF		4.06	NO		3.10mm (0.125)	71780-106LF		
				-				

— NDTE 7 —

NOTES:

CONTACT PLATING: 30u" (0.76um) GOLD PLATING
OVER 50u" (1.27um) NICKLE UNDERPLATE IN CONTACT AREA.
100u" (2.54um) — 200u"(5.08um) TIN PLATING OVER
50u" (1.27um) —100u" (2.54um) NICKEL UNDERPLATE IN
P.C. BOARD LEG AREA. 50u" (1.27um) NICKEL UNDERPLATE OVER REMAINING AREA.

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- CONTACT PLATING: 30u" (0.76um) GXT PLATING OVER 50u" (1.27um) NICKLE UNDERPLATE IN CONTACT AREA. 100u" (2.54um) 200u"(5.08um) TIN PLATING OVER 50u" (1.27um) —100u" (2.54um) NICKEL UNDERPLATE IN P.C. BOARD LÉG AREA. 50u" (1.27um) NICKEL UNDERPLATE OVER REMAINING AREA.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM THICK CIRCUIT BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

CONFIDENTIAL

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